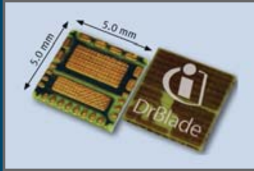
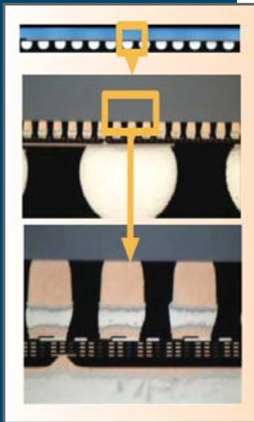
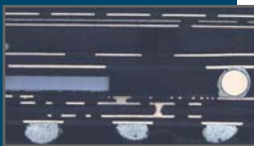
Advanced Packaging Update:
Market and Technology Trends

Vol. 3-0515







The third volume of the Advanced Packaging Update provides an analysis of the outsourced assembly and test (OSAT) industry with revenue trends and planned CAPEX for 2015. A special section focuses on the alternatives to substrates with through silicon vias (TSVs) for split die applications. The report examines trends in power packages with a special section on Cu clip packages. A market update for embedded components is included. An economic outlook based on key economic indicators is provided.

Table of Contents

1 Industry and Economic Trends
- 1.1 Economic Trends
  - 1.1.1 U.S. Macroeconomic Trends
  - 1.1.2 Growth in the Electronics Industry

2 Split Die Package Options
- 2.1 Amkor's SLIM™
- 2.2 Amkor's SWIFT™
- 2.3 Intel's EMIB
- 2.4 SPIL's NTI
- 2.5 Xilinx SLIT

3 Developments in Power Packages
- 3.1 Automotive Electronics
  - 3.1.1 Low-Power Packages
  - 3.1.2 Embedded Components
    - 3.1.2.1 Research Activities
    - 3.1.2.2 Challenges in Automotive Applications
      - 3.1.2.2.1 Temperature
      - 3.1.2.2.2 Isolation Resistance
      - 3.1.2.2.3 Moisture Susceptibility
      - 3.1.2.2.4 Safety Requirements

4 Copper Clip Packages
- 4.1 Companies Offering Cu Clip Packages
  Fairchild Semiconductor, Infineon, NXP, ON Semiconductor, TI, Vishay Siliconix
- 4.2 Assembly Services
  Amkor, ASE, Carsem, Integrated Microelectronics, J-Devices , Nantong Fujitsu Microelectronics, UTAC
- 4.3 Die Attach Material Developments

5 Embedded Die Updates
  ASE, AT&S, Dai Nippon Printing, FlipChip International, Fujikura, GE, Ibiden, Infineon, J-Devices, Kinsus, MST Group, Samsung Electro-Mechanical Company, Schweizer Electronic, Shinko Electric Company, Taiyo Yuden, TDK, TI, Unimicron, Würth Elektronik

List of Figures

1.1. Monthly U.S. housing starts.
2.1. SLIM™ process flow.
2.2. SWIFT™ process flow.
2.3. Intel EMIB.
2.4. NTI-PoP process flow.
3.1. Embedding with thin full area B-stage resin.
3.2. Prepreg with glass fiber for cavity embedding.
4.1. TI's PowerStack™ with Cu clip.
4.2. FET package with Cu clip.
4.3. Dual-die FET package with Cu clip.
4.4. Paste with coated Cu composite particles.
5.1. Infineon DrBlade with embedded die.
5.2. MCeP®
5.3. TI's MicroSiP.

List of Tables

1.1. IC Package Subcontractor Revenue
1.2. Major OSAT Revenue
1.3. Subcontractor CAPEX Growth
2.1. Interposer Solutions without TSVs
3.1. Demand for High Heat-Resistance Technology
3.2. Package Miniaturization, Power Package
3.3. Power High Heat-Resistance Roadmap
4.1. Comparison of Cu Wire, Al Wire, and Cu Clip
4.2. Market Growth for Cu Clip Packages
4.3. ON Semiconductor Packages Using Cu Clip
5.1. Embedded Active and Passive Packages

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